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TABLE OF CONTENTS

Large Cu Wire Wedge Bonding Process for Power Devices	1
<i>J. Ling, T. Xu, C. Luechinger</i>	
Cu Wire Bonding for Fine Pitch 40nm Circuit Under Pad Silicon Integrated Circuits: Development of a Comprehensive Robust Cu Wire Bonding Process.....	6
<i>B. Wang, S. Emerich, K. Davison, N. Rossi, J. Osenbach</i>	
Bondability of Copper Wires on PPF Leadframe	12
<i>T. Wei, J. Ha</i>	
Copper Wirebond Pull Test and Reliability Characterization with Finite Element Simulation.....	20
<i>X. Zhang, J. Teyseyre, K. Goh, W. Wong</i>	
Integration Challenges of Cu Pillars with Extreme Wafer Thinning for 3D Stacking and Packaging.....	25
<i>T. Buisson, G. Potoms, A. Phommahaxay, G. Verbinen, P. Jaenen, A. Manna, Y. Travaly, E. Beyne</i>	
Nonlinear Copper Behavior of TSV for 3D-IC-Integration and Cracking Risks during BEoL-Built-up	29
<i>J. Auersperg, D. Vogel, E. Auerswald, S. Rzepka, B. Michel</i>	
Thermo-mechanical Impact of the Underfill-microbump Interaction in 3D Stacked Integrated Circuits	34
<i>A. Ivankovic, B. Vandeveld, K. Rebibis, A. Manna, G. Plas, V. Cherman, E. Beyne, I. Wolf, D. Vandpitte</i>	
Near Term Solutions for 3D Packaging of High Performance DRAM	39
<i>V. Solberg, W. Zohni</i>	
Electroless Ni-W-P Alloy As A More Enduring And Reliable Soldering Metallization	44
<i>Y. Yang, J. Balaraju, Z. Tsakadze, Z. Chen</i>	
Interfacial Microstructure And Mechanical Reliability Of Cu Pillar/Sn-3.5Ag Bump For 3D Packages.....	49
<i>B. Kwak, J. Kim, M. Jeong, K. Lee, J. Kim, Y. Park</i>	
Reliability of Copper Wire Bonding in Humidity Environment.....	53
<i>H. Liu, Z. Zhao, Q. Chen, J. Zhou, M. Du, S. Kim, J. Chae, M. Chung</i>	
Addressing Delamination for Fast Development of Reliable Packages.....	59
<i>W. Kanert, R. Pufall</i>	
Heat Conduction across Multiwalled Carbon Nanotube/Graphene Hybrid Films	63
<i>X. Li, L. Jarvis, K. Liang, B. Tay, D. Baillargeat</i>	
Measurement Based Compact Thermal Model Creation - Accurate Approach to Neglect Inaccurate TIM Conductivity Data	67
<i>A. Vass-Varnai, R. Bornoff, Z. Sarkany, S. Ress, M. Rencz</i>	
Thermal Design, Analysis and Optimization of a Power Charger for Hybrid or Electric Vehicles	73
<i>L. Biswal, S. Kumar</i>	
Thermal Performance Evaluation of a Synthetic Jet Heat Sink for Electronic Cooling.....	79
<i>T. Chandratilleke, R. Narayanaswamy, D. Jagannatha</i>	
MEMS Technology on Wafer-level LED Packaging	84
<i>C. Chang, C. Huang, T. Lai, C. Tsou, T. Hwang, C. Chen</i>	
Sinter Adhesive – New Horizons in Semiconductor Packaging	88
<i>Y. Lower, T. Krebs, M. Thomas</i>	
Design, Manufacturing and Packaging of High Frequency Micro Ultrasonic Transducers for Medical Applications.....	93
<i>J. Ng, R. Ssekitoleko, D. Flynn, R. Kay, C. Demore, S. Cochran, M. Desmulliez</i>	
Design and Fabrication of a Novel Monolithic Integration Structure for Un-cooled Infrared Focal Plane Array and Readout IC	99
<i>S. Ma, X. Sun, Y. Zhu, Q. Cui, Y. Jin, X. Yu, J. Chen, M. Miao</i>	
Understanding The Electrical Transport Properties Of Carbon Nanotubes And Its Metal Under-Layers	104
<i>D. Tan, C. Yap, X. Li, J. Wei, D. Baillargeat, B. Tay</i>	
Low Standoff Chip to Wafer Bonding	108
<i>S. Chong, D. Wee, K. Teo</i>	
Thin Wafer Processing - Yield Enhancement Through Integrated Metrology	113
<i>T. Matthias, D. Burgstaller, J. Burggraf, P. Kettner, M. Wimplinger, P. Lindner</i>	
Cost Effective 300mm Large Scale eWLB (Embedded Wafer Level BGA) Technology	117
<i>M. Prashant, S. Yoon, Y. Lin, P. Marimuthu</i>	
Developments of Blade Dressing Technique Using SiC Board for C90 Low-K Wafer Sawing.....	122
<i>K. Shi, K. Yow, R. Khoo</i>	

Performances Of Wafer-Level Underfill With 50µm Pitch Interconnections: Comparison With Conventional Underfill	129
<i>A. Taluy, S. Lhostis, A. Jouve, G. Garnier, E. Dezandre, A. Farcy, S. Cheramy, N. Sillon, A. Sylvestre</i>	
A Introduction of sFCCSP – Fine Pitch Low Profile FCCSP Solution	135
<i>E. So, A. Lan, C. Hsiao, N. Chang, F. Kao</i>	
Microvia Reliability Improvement for High Density Interconnect Substrate	138
<i>B. Xiong, K. Loo, K. Nagarajan</i>	
Development of Radio-opaque Micro Tag for Tagging Module in Capsule Endoscope Applications	142
<i>L. Ruiqi, R. Katayan, K. Vaidyanathan</i>	
Moisture Characteristics of Wafer Level Compression Molding Compounds	147
<i>R. Rajoo, X. Zhang</i>	
Design Optimization and Performance Verification of Multi-channel High-speed Optical Transceiver Package	153
<i>F. Liu, L. Wan, J. Zhou, B. Li, T. Du, W. Gao, F. Wan</i>	
Hybrid EM/Circuit Modeling for Carbon Nanotubes based Interconnects	158
<i>C. Brun, P. Franck, Y. Chong, D. Tan, E. Tong, S. Bila, D. Baillargeat, B. Tay</i>	
New Circuit Model for Modeling Differential Pair of Through-hole Vias in Multilayered Electronic Packages	163
<i>Z. Oo,</i>	
Plasmon Resonances of Carbon-nanotube-based Dipole Antennas for Nano-Interconnects	167
<i>P. Franck, C. Brun, Y. Chong, D. Tan, E. Tong, S. Bila, D. Baillargeat, B. Tay</i>	
Electrical Modeling, Simulation And SPICE Model Extraction Of TSVs In Silicon Interposer	171
<i>X. Sun, Y. Zhu, S. Ma, M. Miao, J. Chen, Y. Jin</i>	
Newly Developed In-situ Formation of SnAg and SnAgCu Solder on copper Pillar Bump	175
<i>F. Dai, D. Yu, W. Yin, N. Zhao, L. Wan, H. Yu, S. Wang, J. Sun</i>	
Silver-Polyaniline-Epoxy Electrical Conductive Adhesives – A Percolation Threshold Analysis	180
<i>S. Gunfekar, A. Chen, B. Zhao</i>	
Ultra Low Temperature Curable Anisotropic Conductive Films (ACFs) With Photo Latent Curing Behavior (PLC-ACFs)	185
<i>I. Kim, K. Paik</i>	
High Thermal Performance ICP Die Attach Process Design and Development for LQFP-EP	190
<i>L. Yee, K. Hoon, T. Bee, Y. Yun</i>	
Characterization of CNT Interconnection Bumps Implemented for 1st Level Flip Chip Packaging	195
<i>C. Yap, D. Tan, C. Brun, E. Teo, J. Wei, B. Dominique, B. Tay</i>	
Development of High Resolution Imaging Modules for Wireless Endoscopic Applications	199
<i>R. Katayan, L. Ruiqi, K. Vaidyanathan</i>	
Packaging Development for GaAs X-Ray Line Detectors	203
<i>M. Oppermann, O. Albrecht, T. Lohse, R. Metasch, T. Zerna, K. Wolter</i>	
MEMS Tri-axial Tactile Sensor Packaging using Polymer Flexible Cable for Sensorised Guide Wire Application	207
<i>M. Hamidullah, M. Cheng, L. Lim, C. He, H. Feng, W. Park</i>	
High-Performance Photonic Crystal Device Fabrication Process Module Development for Photonics Application	211
<i>D. Wei, X. Luo, N. Leekian, Y. Mingbin</i>	
Design of LED Packaging Module for Automotive Forward-lighting Application	213
<i>F. Chen, K. Wang, M. Zhao, Z. Mao, J. Yao, C. Li, S. Liu</i>	
Joint Properties of Au Stud Bumps Joined with Sn-3.5Ag Solder by Flip Chip Bonding	218
<i>Y. Lee, Y. Ko, S. Yoo, C. Lee</i>	
NCA Flip-Chip Bonding with Thermoplastic Elastomer Adhesives - Fundamental Failure Mechanisms and Opportunities of Polyurethane Bonded NCA-Interconnects	223
<i>P. Foerster, T. Linz, M. Krshiwoblozki, H. Walter, C. Kallmayer, R. Aschenbrenner</i>	
Study on the Characteristics of Various Dopants in Sn-1Ag-0.8Cu Solder	231
<i>J. Son, Y. Lee, S. Hong, I. Im, J. Lee, H. Kim, J. Moon</i>	
Low Cost fcCSP Based on Cu Pillar	236
<i>B. Appelt, H. Chung, C. Chen, R. Wang, M. Hung</i>	
Carbon Nanotube Network Transistors Prepared From Agarose Gel Separation Methods	240
<i>J. Tey, E. Kok, H. Lu, J. Wei</i>	
Screen Printed Thick Film Subterranean and Subaqueous Environmental Chemical Sensor Arrays	245
<i>J. Atkinson, M. Glanc, M. Prakorbjanya, R. Sion, E. Garcia-Breijo</i>	
Low Temperature Processing of Copper Conductive Ink for Printed Electronics Applications	251
<i>B. Salam, W. Lai, L. Albert, L. Keng</i>	

Optimization and Characterization of Drop-on-demand Inkjet Printing Process for Platinum Organometallic Inks	256
<i>G. Cummins, R. Kay, J. Terry, M. Desmulliez, A. Walton</i>	
Assessment of the Accuracy of Cure Kinetics Models and Fitting Approaches Utilised in Analysis of Microelectronics Encapsulation Materials	262
<i>T. Tilford, M. Ferenets, R. Adamietz, S. Pavuluri, M. Desmulliez, C. Bailey</i>	
Design Analysis and Optimization of Metal Core BGAs for Warpage	268
<i>H. Kang, J. Park, S. Oh</i>	
Improving Predictability of Wire-Sweep in Cavity Filling Analysis	272
<i>N. Subramanian, T. Tong, K. Ian, P. Heinz</i>	
Electromigration in Electroplated Gold Micro Contacts	277
<i>J. Kleff, G. Engelmann, H. Oppermann, H. Reichl</i>	
Green Mould Compounds: Impact on Second Level Interconnect Reliability	283
<i>B. Vandeveldde, M. Lofrano, G. Willems</i>	
Growth Characteristic Study of Intermetallic Compounds Growth in Nanoscale-thickness Cu/Sn/Cu Sandwich Structure	289
<i>Q. Li, Y. Chan, S. Ismathullakhan</i>	
Impact of Palladium to the Interfacial Behavior of Palladium Coated Copper Wire on Aluminium Pad Metallization during High Temperature Storage	294
<i>D. Stephan, E. Chew, J. Yeung, E. Milke</i>	
Ultra Fine Pitch Bare Cu Wire Bonding Manufacturability Control For Plastic Ball Grid Array Device	304
<i>S. Teck, J. Tin, L. Khoon, N. Kalandar</i>	
Characterization of Palladium Coated Copper Wire Prior Physical Bonding Assessment	313
<i>Y. Lin, W. Juergen</i>	
Influence of Nitrogen and Forming Gas towards Palladium Coated Copper Wire	318
<i>M. Ching, K. Lee</i>	
Copper Wire Bonding Process in Leaded Packages with Zero Loss in Quality, Capacity, Scrap & Machine Efficiency	324
<i>T. Eng</i>	
Development of Thermal Compression Bonding with Non Conductive Paste for 3DIC Fine Pitch Copper Pillar Bump Interconnections	329
<i>C. Chan, W. Tseng, H. Huang, P. Huang, M. Chan, C. Lin, M. Liu, C. Chiu, S. Chiu, M. Ma</i>	
Development for VCI (Vertical Circuit Interconnection) Technology for Stacked Die Package	333
<i>I. Chang, J. Tsai, J. Chiang, D. Liu, F. Tsai, D. Shih, E. Tung</i>	
2.5D/3D TSV Processes Development and Assembly/Packaging Technology	336
<i>S. Yoon, D. Na, K. Choi</i>	
Redistribution Layer (RDL) Process Development and Improvement for 3D Interposer	341
<i>H. Li, H. Chua, F. Che, A. Trigg, K. Teo, S. Gao</i>	
Ultra-High Selectivity TSV Etching Hardmask Process Development and Integration for 3D-SIC	345
<i>G. Lau, S. Praveen, S. Lee, W. Loh, D. Wei, J. Paulasaari, D. Thomas, M. Laukkanen, W. McLaughlin, J. Rantala, H. Li, G. Shan</i>	
Advances in Spray Coating Technologies for MEMS, 3DICs and Additional Applications	349
<i>E. Pabo, H. Kurotaki, P. Lindner, T. Matthias, P. Kettner</i>	
Measurement Methods for Curing Properties of Resin Considering Process Condition and Effects on Package	354
<i>T. Takeda, Q. Yu</i>	
Development of Integrated Passives QFN Package	358
<i>E. Keong</i>	
Build-up Electrical Insulation Material with Low-Dielectric Loss Tangent, Low-CTE and Low-Surface Roughness	363
<i>E. Horiki, I. Suzuki, T. Tanaka, A. Uenishi, K. Shiomi</i>	
Ultra Low Cost Advanced Package Solution –Cu Via Microstar CSP (CV-u*CSP) Development	369
<i>J. Ho, M. Chen, A. Li</i>	
Copper High Volume Manufacturing R&D to Production	374
<i>B. Chylak, H. Clauberg, J. Foley, I. Qin, B. Milton</i>	
The Microstructure and Texture Evolution in the Heat Affected Zone of Copper Bonding Wire	382
<i>D. Liu, H. Chen, F. Wong, K. Lee, I. Shiu, J. Wu</i>	
Is Copper Wire Bonding Ready for Automotive Applications?	387
<i>B. Appelt, A. Tseng, L. Huang, S. Chen</i>	
Challenges of Pd-coated Cu Wire Bonding on C65 Al Bond Pad Low-k Wafer with BOA Structure	391
<i>C. Jin, N. Christine, C. Ting, D. Tong</i>	

Temperature Soak Reliability of Laser-Sintered Ag Pads for Wire Bonding	397
<i>K. Yamasaki, K. Maekawa, T. Niizeki, M. Mita, Y. Matsuba, N. Terada, H. Saito</i>	
Low Cost Characterization of the Electrical Properties of Thin Film and Mold Compound for Embedded Wafer Level Packaging (EMWLP)	401
<i>L. Ying, D. Wee, K. Joon, P. Damaruganath</i>	
Numerical Study of Preventing Flow-induced Die-shift in the Compression Molding for Embedded Wafer Level Packaging	406
<i>L. Ji, H. Kim, F. Che, S. Gao, D. Pinjala</i>	
Embedded Wafer Level BGA (eWLB) – Extra-small and eLGA Packages	412
<i>R. Anandan, Y. Huang, Y. Jin, K. Gan, P. Chua, Y. Liu, J. Alvin</i>	
Development of Via in Mold (ViM) for Embedded Wafer Level Package (EWMLP)	417
<i>S. Ho, M. Pa, F. Daniel, W. Lee, S. Chong, H. Kim, P. Damaruganath, G. Shan</i>	
Embedded Wafer Level Ball Grid Array (eWLB) Technology for Millimeter-Wave Applications	423
<i>M. Wojnowski, R. Lachner, J. Bock, C. Wagner, F. Starzer, G. Sommer, K. Pressel, R. Weigel</i>	
Optimization of IQ Mismatch Test	430
<i>G. Heng, T. Boon</i>	
Customized Jig For Test Debug	435
<i>P. Feng, W. Sun</i>	
FE-Simulation of Inductively Excited Lock-in Thermography for Electronic Interconnections	439
<i>J. Bohm, K. Wolter</i>	
Characterization of High Performance CNT-based TSV for Radar Applications	445
<i>B. Kim, S. Kannan, A. Gupta, S. Noh, L. Li</i>	
Effect of Microstructure on Thermal-Mechanical Stress in 3D Copper TSV Structures	450
<i>Z. Wu, Z. Huang, P. Conway, Y. Ma</i>	
Challenges and Approaches of TSV Thin Die Stacking on Organic Substrate	455
<i>S. Pei-Siang, C. Faxing, C. Choong, M. Rong, V. Sekhar, V. Rao, C. Chong</i>	
Underfill Characterization for Multi-layer 3D-SiP Stacked Chip Package	462
<i>M. Chew, E. Wai, C. Heang, D. Ho, S. Lim, S. Chong, T. Chai, V. Rao</i>	
Stacking of Known Good Reconstructed Wafer without TSV Applications to Memory-only and Heterogeneous SiP	469
<i>C. Val, P. Couderc, J. Noiray, N. Boulay</i>	
Study of Interaction between Cu-SnAg and Ni-SnAg Interfacial Reactions by Low Solder Volume in 3D IC Packaging	474
<i>H. Hsiao, Y. Huang, C. Chen</i>	
IMC Study on Cu Wirebond Failures under High Humidity Conditions	480
<i>Y. Yamaji, M. Hori, H. Ikenosako, Y. Oshima, T. Suda, A. Umeki, M. Kandori, M. Oida, H. Goto, A. Katsumata, Y. Hiruta</i>	
Application Of Hybrid Methods To Analyse Interface Properties Of Packaging Materials On Miniaturized Specimens	486
<i>H. Walter, B. Wunderle, J. Keller, O. Holck, O. Wittler, B. Michel</i>	
Mechanical Properties and Joint Reliability Improvement of Sn-Bi Alloy	492
<i>J. Wang, L. Wen, J. Zhou, M. Chung</i>	
Process and Material Effects on BGA Board Level Solder Joint Reliability	497
<i>S. Meyer, R. Metasch, R. Schwerz, H. Wohlrabe, K. Wolter</i>	
To Inhibit the Consumption of Cu During Multiple Reflows of Pb-free on Cu	503
<i>C. Hu, H. Hsiao, M. Guo, C. Chen, K. Tu</i>	
Novel Dual Layer Electroformed Stencils for High Resolution LTCC Circuit Manufacture	507
<i>R. Kay, G. Cummins, M. Desmulliez, J. Terry, A. Walton</i>	
A New Dual-Band Wilkinson Power Divider Using Arbitrary-Length Dual Transmission Lines	513
<i>J. Guo, L. Dai, P. Deng</i>	
Processing and Characterization of Flexographic Printed Conductive Grid	517
<i>L. Keng, W. Lai, L. Albert, B. Salam</i>	
Formation of Large Format Functional Films via Roll-to-Roll (R2R) Ultraviolet (UV) Embossing	521
<i>X. Shan, S. Lau, M. Mohahidin, T. Liu, A. Lu</i>	
A Simplified Approach to Simulate Bubble Nucleation in Flow Boiling	525
<i>X. Xing, Y. Lee, Y. Hoe, X. Zhang, S. Gao, D. Pinjala</i>	
Experimental Investigation of Microgap Cooling Technology for Minimizing Temperature Gradient and Mitigating Hotspots in Electronic Devices	530
<i>T. Alam, P. Lee, C. Yap, L. Jin</i>	
A Study on Cooling Efficiency Improvement of Thin Film Transistor Liquid Crystal Display (TFT-LCD) Modules	536
<i>M. Iz, I. Tavman, A. Turgut</i>	

Mitigation of Thermal Fatigue Failure in Fully Underfilled Lead-free Array-based Package Assemblies Using Partial Underfills	542
<i>H. Shi, T. Ueda</i>	
Thermal Modeling and Characterization of Package with Through-Silicon-Vias (TSV) Interposer	548
<i>X. Xing, Y. Lee, T. Tee, X. Zhang, S. Gao, W. Kwon</i>	
Embedded Passive and Active Package using Silicon Substrate.....	554
<i>J. Yook, J. Kim, D. Kim, J. Park</i>	
Embedded Component Substrates Moving Forward	558
<i>B. Appelt, B. Su, D. Lee, U. Yen, M. Hung</i>	
Low Temperature Packaging of BioMEMS and Lab-on-chip Devices	562
<i>T. Matthias, R. Miller, C. Thanner, D. Burgstaller, G. Kreindl, V. Dragoi, P. Kettner, P. Lindner</i>	
A Novel High Melting Lead-Free Mixed Solder Paste System.....	567
<i>H. Zhang, N. Lee</i>	
Post Cure Behaviour of Encapsulants for QFN Packages Processed by an Open-Ended Single Mode Resonant Microwave Applicator	573
<i>S. Pavuluri, M. Desmulliez, G. Goussetis, V. Arrighi, K. Johnston, R. Adamietz, T. Tilford, C. Bailey</i>	
Investigation on the Optimum Sampling Rate of Strain Measurement during Printed Circuit Board (PCB) System Assembly	579
<i>H. Shi, T. Ueda</i>	
Yield And Productivity Improvements Through Use Of Advanced Dual Plasma Source For TSV Reveal & Wafer Dicing Applications	585
<i>R. Barnett, D. Thomas, H. Griffiths</i>	
Decoupling Capacitance for the Power Integrity of 3D-DRAM-Over-Logic System.....	590
<i>W. Ahmad, Q. Chen, L. Zheng, H. Tenhunen</i>	
Development of Copper Via Exposure by Two Steps Process.....	595
<i>O. Joe, L. Vincent, G. Shan</i>	
TSV Via-Last: Optimization of Multilayer Dielectric Stack Etching.....	600
<i>L. Leng, H. Li, K. Teo, R. Murthy, E. Kiat</i>	
High Speed Full Wafer Monitoring Of Surface, Edge And Bonding Interface For 3D-Stacking	604
<i>P. Guittet, L. Markwort, G. Savage, C. Kappel, S. Halder, A. Phommahaxay, A. Jourdain, A. Miller</i>	
Multi Chip Stacking & Reliability Challenges using TSV-Micro C4 Solder Interconnection for FCCSP TSV Package	608
<i>K. Au, J. Beleran, Y. Yang, Y. Zhang, S. Kriangsak, P. Wilson, Y. Drake, S. Nathapong</i>	
Bonding Wire Options and Their Impact on Product Reliability.....	620
<i>C. Vath III, R. Holliday</i>	
Reliability of Various Pb-free Solders under Vibration and Elevated Temperature Environments.....	626
<i>Y. Ko, Y. Lee, S. Yoo, C. Lee</i>	
Prototyping of Low-cost Wafer Level Packages.....	631
<i>H. Chen, T. Tee, G. Siew, S. Soh, I. Kang, J. Kim, T. Lee, B. Ser, H. Ng, G. Hoe, S. Gao</i>	
Design for Reliability of Hi-density Leadless Array (HLATM) Package.....	636
<i>Y. Yang, P. Serafin, B. Zheng, S. Nathapong, T. Edward, C. Surasit</i>	
Lock-in Thermography Application in Flip-chip Packaging for Short Defect Localization	642
<i>M. Tay, M. Tan, W. Qiu, X. Zhao</i>	
Numerical Simulations of Forced Convection in Novel Cylindrical Oblique-Finned Heat Sink.....	647
<i>Y. Fan, P. Lee, L. Jin, B. Chua</i>	
Enhanced Heat Transfer and Reduced Pressure Drop Using Stepped Fin Microchannels.....	653
<i>K. Balasubramanian, P. Lee, L. Jin, S. Chou, C. Teo, S. Gao</i>	
Submerged Liquid Jet Impingement Cooling	660
<i>Z. Wang, T. Wong, F. Duan</i>	
Effects of Package and Mold Cavity Structures on the Wire Sweep Behavior during Package Array Transfer Molding.....	667
<i>J. Han, H. Chen, F. Wong, K. Leung, I. Shiu, J. Wu</i>	
Board Level Solder Joint Reliability Modeling of Embedded Wafer Level BGA (eWLB) Packages under Temperature Cycling Test Conditions.....	674
<i>S. Chow, W. Choi, R. Emigh, E. Ouyang</i>	
Damage Progression in BGA Solder Joints during Board-Level Drop Test.....	681
<i>A. Yamin, N. Shaffiar, W. Loh, M. Tamin</i>	
Nonlinear Thermal Stress & Strain Analysis of Through Silicon Vias with Different Structures and Polymer Filling.....	686
<i>J. Zhou, D. Yu, R. He, W. Feng, X. Guo, C. Song, H. Wang, D. Guidotti, L. Cao, L. Wan</i>	
Surface Materials Analysis of Defect Ring on Image Sensor	691
<i>B. MacDonald, Z. Xing, C. Fu, X. Li</i>	

TSV Diagnostics by X-ray Microscopy	695
<i>K. Sueoka, F. Yamada, A. Horibe, H. Kikuchi, K. Minami, Y. Orii</i>	
Failure Isolation for Advanced Packages Using Time-Domain Reflectometry	699
<i>B. Zheng, C. Hunat, W. Yuan, N. Suthiwongsunthorn, S. Chungpaiboonpatana</i>	
Investigation of Ultrasonic Pd Coated Cu Wire Wedge Bonding on Different Surface Finish	705
<i>L. Hung, D. Jiang, C. Huang, Y. Wang</i>	
Non-destructive Inspection of through Mould vias in Stacked Embedded Packages by Micro-CT	710
<i>H. Roth, T. Neubrand</i>	
A New Tool Development for the Thermal Design and Quick Performance Evaluation of D2-FBGA Devices	714
<i>S. Ore, K. Gan, J. Tamil, N. Suthiwongsunthorn, S. Chungpaiboonpatana</i>	
Thermal Analysis of High Brightness Flip-chip LED Packages	722
<i>P. Qin, Q. Li, Y. Chan</i>	
Multi-objective Optimization of a Radial Heat Sink considering Radiation Effect	726
<i>D. Jang, S. Yu, K. Lee</i>	
A Novel Wafer Level Fan-out Package (WFOP™) Applicable to 50um Pad Pitch Interconnects	730
<i>N. Hayashi, T. Takahashi, N. Shintani, T. Kondo, H. Marutani, Y. Takehara, K. Higaki, O. Yamagata, Y. Yamaji, A. Katsumata, Y. Hiruta</i>	
Innovative MEMS Wafer Level Packaging on Bonding, Molding and Assembly Process	734
<i>C. Liu, H. Chang, H. Liao, K. Li, C. Lin, J. Huang</i>	
Advanced Packaging Solutions of Next Generation eWLB Technology	739
<i>Y. Jin, J. Teyseyre, X. Baraton, S. Yoon, Y. Lin, P. Marimuthu</i>	
Advanced Processes and Materials for Temporary Wafer Bonding	744
<i>J. McCutcheon, D. Blumenshine, A. Lee</i>	
Evaluation And Optimization Of Die-Shift In Embedded Wafer-Level Packaging By Enhancing The Adhesion Strength Of Silicon Chips To Carrier Wafer	747
<i>J. Mazuir, V. Olmeta, M. Yin, G. Pares, A. Planchais, K. Inal, M. Saadaoui</i>	
Fine Pitch Copper Wire Bonding on 45nm Tech Cu/low-k Chip With Different Bond Pad Metallurgy	752
<i>L. Wai, N. Jaafar, M. Chew, Sivakumar, Gunasekaran, Kanchet, D. Witarasa, T. Boon, V. Srinivasa, T. Chai, Alastair, J. Woo</i>	
Fine Pitch Copper Wire Bonding Process Optimization with 33µm Size Ball Bond	758
<i>N. Jaafar, W. Ching, V. Rao, C. Chong, A. Trigg, G. Kanchet, Sivakumar</i>	
Wire Diameter and Length Effects on Wire Sweep Performance of Multi-tier Copper and Gold Wire Bonding in Plastic Ball Grid Array Packages	764
<i>S. Hian, F. Seng, T. Kiong, N. Kalandar</i>	
New Method For Decapsulation Of Copper Wire Devices Using LASER And Sub-Ambient Temperature Chemical Etch	769
<i>M. Lefevre, F. Beauquis, J. Yang, M. Obein, P. Gounet, S. Barberan</i>	
Development of Through Glass Tungsten Via Interconnect for 3D MEMS Packaging	774
<i>Y. Sun, D. Yu, S. Yang, X. Sun, J. Zhang, X. Wei, L. Wan</i>	
Evaluation of Ultra Thick Photo Resist for High Aspect Ratio Bumping Applications	777
<i>D. Fernandez, V. Rao, S. David, W. Justin, L. Siow</i>	
Matching-Assisted Self-Assembly For Thin Chips	781
<i>H. Chua, D. Ho, L. Siow, V. Kripesh</i>	
Integration of Low Profile Neural Probe Array with Flexible Polyimide Cable	785
<i>T. Ling, C. Yuan, T. Giao, P. Tae, J. Minkyu</i>	
Influence of Cu Columns on Current Crowding Effect in Electromigration in Flip-Chip Solder Joints	789
<i>Y. Liang, W. Tsao, D. Yao, Y. Lai, C. Chen</i>	
Cu Wire Bonding in Ni/Pd/Au-Ag and Roughened Ni/Pd/Au-Ag Pre-plated Leadframe Packages	794
<i>W. Li, A. Acuesta, M. Mercado, N. Malonzo, R. Cabral</i>	
Extraction of Transceiver Die Pin Capacitance Using S-Parameter De-embedding Technique with Distributed Circuit Modeling	798
<i>L. Chyan, L. Ngik, H. Shi</i>	
DC Analysis for Power Delivery in Board Design by Post-layout Simulation	802
<i>W. Wong</i>	
Heat Affected Zone and Inter-metallic's Formation in Gold Wire Thermosonic Bonding as Function of Wire Material	805
<i>J. Premkumar, M. Gopinath, M. Shie, G. Tay</i>	
Dishing Study of Polyimide CMP Process	810
<i>Y. Mao, G. Chen, R. Murthy, E. Tan, W. Loh</i>	
Electrical Functionalization of Thermoplastic Materials by Aerosol Jet Printing	813
<i>J. Hoerber, C. Goth, J. Franke, M. Hedges</i>	

An Investigation into Damage-Free Thin Die Pick and Place for 3D Stacking	819
<i>K. Malachowski, D. Gonzales, R. Miller, F. Schnegg, A. Arzberger, Z. Hajdarevic, A. LaManna</i>	
CSP Package and Ball Design for Board Level Characteristic	824
<i>Y. Wang, V. Lin, E. Chen, D. Lee</i>	
Thermal Fatigue Life Simulation on DDR3 Package.....	829
<i>N. Wan</i>	
Characterization of Room Temperature E-beam Evaporated Ge Thin Film.....	834
<i>J. Xie, C. Toh, W. Catherine, D. Wei</i>	
Study on Thermal Boundary Conductance Between Diamond and Amorphous Carbon	837
<i>N. Khosravian, M. Samani, G. Loh, M. Shakerzadeh, D. Baillargeat, B. Tay</i>	